

<b>0.51 Inch Two Digit Display SMD</b>
<b>OSL2051A-IX (Common Anode type)</b>
<b>OSL2051A-LX (Common Cathode type)</b>

■ **Features**

- 0.51 Inch Two Digit Display
- Long lifetime operation
- IC compatible
- Low power dissipation
- Black surface & white segment or dot
- RoHS compliant

■ **Applications**

- Counting device
- Clock

■ **Absolute Maximum Rating (Ta=25°C)**

Item	Symbol	Value		Unit
		W/B/TG	YG/Y/O/R/RA	
DC Forward Current	I <sub>F</sub>	25	25	mA
Pulse Forward Current*	I <sub>FP</sub>	80	80	mA
Reverse Voltage	V <sub>R</sub>	5	5	V
Power Dissipation	P <sub>t</sub>	90	65	mW
Operating Temperature	Topr	-30~ +85		°C
Storage Temperature	Tstg	-40~ +100		°C
Lead Soldering Temperature(1.6mm Below body)	Tsol	260°C/3sec		°C

\*Pulse width Max.10ms Duty ratio max 1/10

\*Reflow time Max.3seconds

■ **Electrical -Optical Characteristics (Ta=25°C)**

Part Number	Color		V <sub>F</sub> (V)			I <sub>R</sub> (μA)	I <sub>v</sub> (mcd)			λD(nm)		
			Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.
			I <sub>F</sub> =20mA			V <sub>R</sub> =5V	I <sub>F</sub> =10mA			I <sub>F</sub> =20mA		
OSL2051A-IW(LW)	White	W	2.8	3.1	3.6	100	30	60	-	6000K	8000K	10000K
OSL2051A-IB(LB)	Blue	B	2.8	3.1	3.6	100	6	12	-	460	465	475
OSL2051A-IG(LG)	True Green	TG	2.8	3.1	3.6	100	15	24	-	510	520	530
OSL2051A-IYG(LYG)	Yellow Green	YG	1.8	2.1	2.6	100	4	6	-	565	570	575
OSL2051A-IY(LY)	Yellow	Y	1.8	2.1	2.6	100	5	9	-	585	590	595
OSL2051A-IO(LO)	Orange	O	1.8	2.1	2.6	100	5	9	-	600	605	610
OSL2051A-IR(LR)	Red	R	1.8	2.1	2.6	100	5	9	-	625	630	640

\*1 Tolerance of measurements of chromaticity coordinate is ±10%

\*2 Tolerance of measurements of dominant wavelength is ±1nm

\*3 Tolerance of measurements of luminous intensity is ±15%

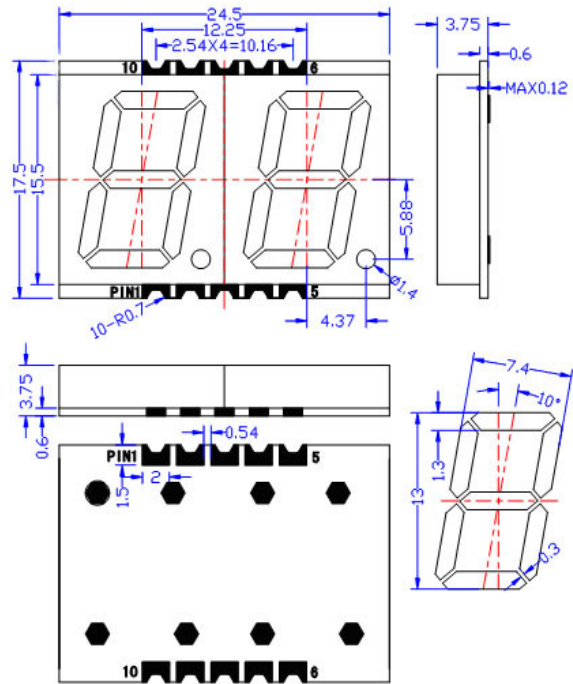
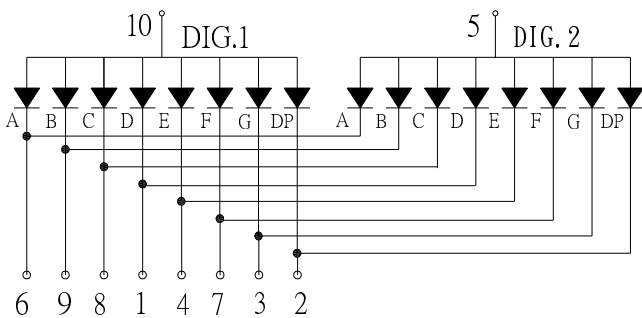
\*4 Tolerance of measurements of forward voltage is ±0.1V

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■ Package Dimensions

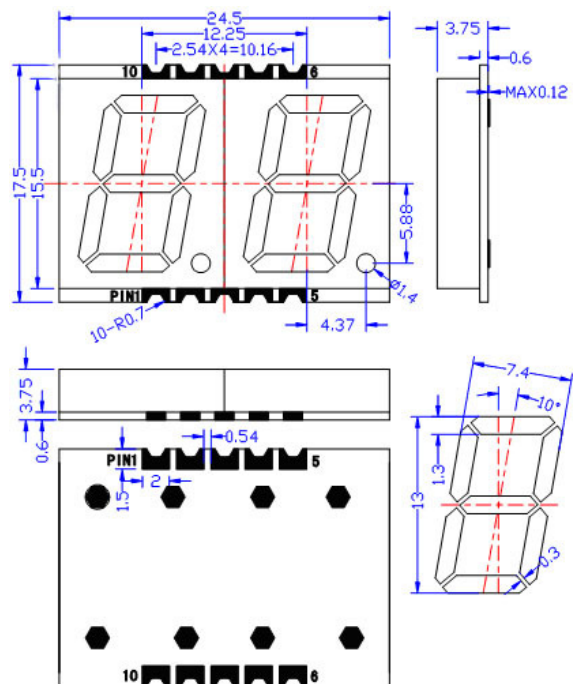
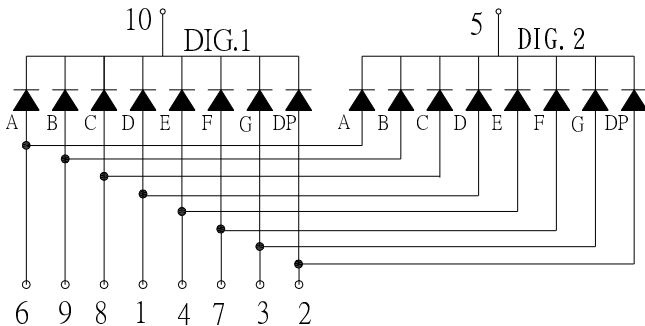
**OSL2051A-IX  
(Common Anode type)**

Note:  
1,Unit : mm( Tolerance:±0.25mm unless otherwise noted)

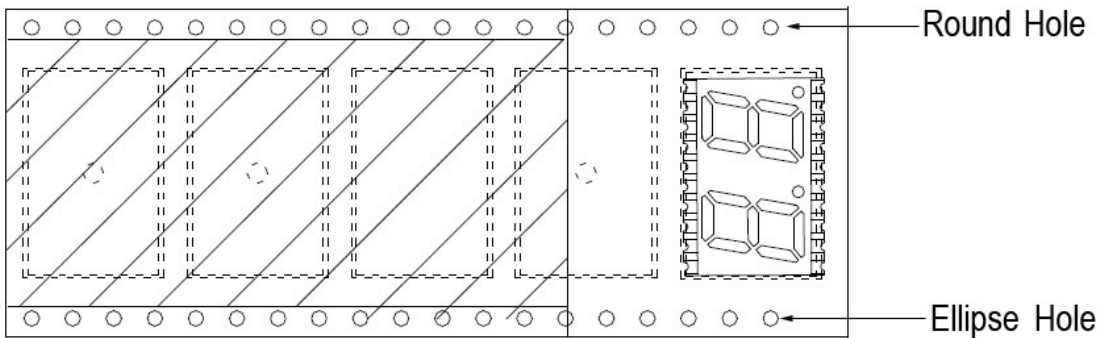


**OSL2051A-LX  
(Common Cathode type)**

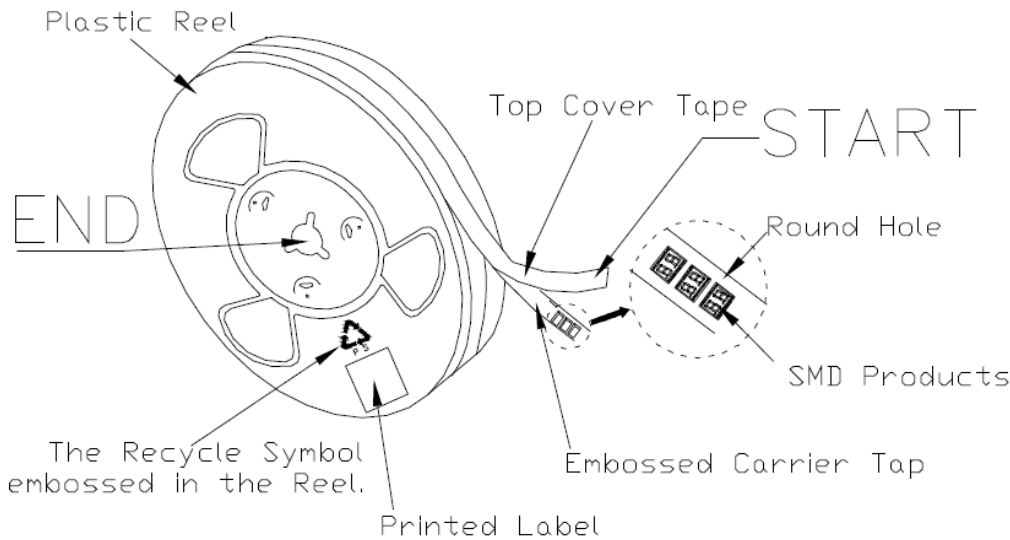
Note:  
1,Unit : mm( Tolerance:±0.25mm unless otherwise noted)



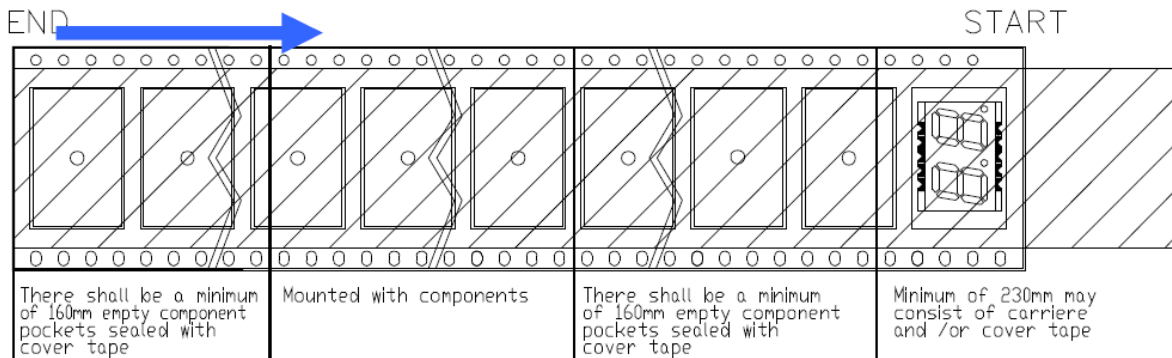
**■ The Products In The Reel Of Direction**



**■ Label Direction & Content In The Roll**



**■ USER FEED DIRECTION**



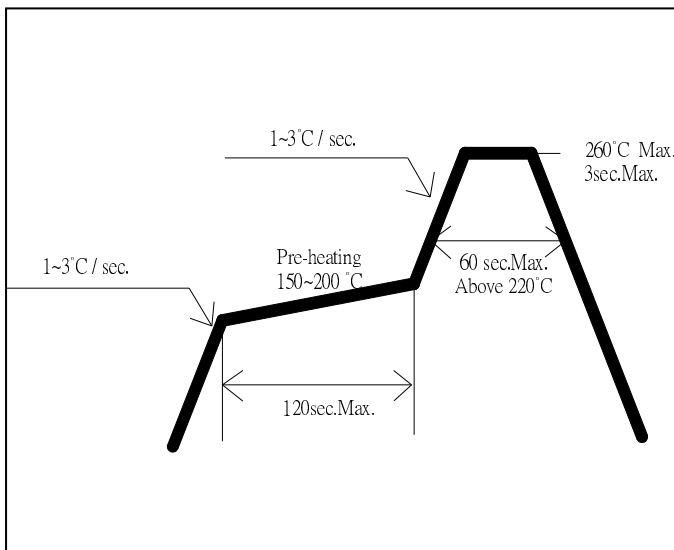
**■ Package Criteria:**

1. Total unit per reel is 500PCS.
2. Max 5 reels/2500PCS are packaged in each carton

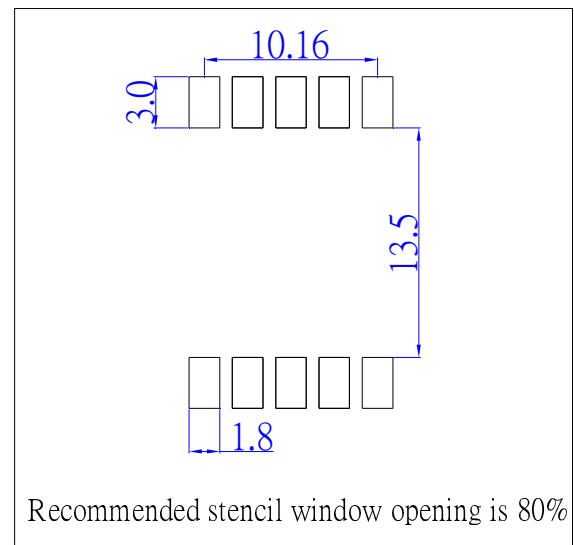
■ **Soldering Conditions**

Reflow Soldering		Hand Soldering	
Pre-Heat	150 ~ 200°C	Temperature Soldering time	350°C Max. 3 sec. Max. (one time only)
Pre-Heat Time	120 sec. Max.		
Peak temperature	260°C Max.		
Dipping Time	<b>3 sec. Max.</b>		
Condition	Refer to Temperature-profile		

• **Reflow Soldering Condition(Lead-free Solder)**



• **Recommended Soldering Pattern(unit:mm)**

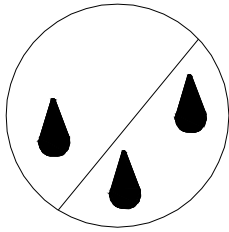


\*Recommended soldering conditions vary according to the type of LED

\*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.

\*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

- All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.



# CAUTION

This bag contains

## MOISTURE-SENSITIVE DEVICES

LEVEL

3

1. Calculated shelf life in sealed bag: 12 months at  $<40^{\circ}\text{C}$  and  $<90\%$  relative humidity (RH).
2. Peak package body temperature: Per Product Label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
  - a) Mounted within: 168 hours of factory conditions  $\leq 30^{\circ}\text{C}/60\% \text{RH}$
  - b) stored per J-STD-033
4. Devices require bake, before mounting, if:
  - a) Humidity Indicator Card is  $>10\%$  when read at  $23 \pm 5^{\circ}\text{C}$
  - b) 3a or 3b not met.
5. If baking is required, devices may be baked for 20 hours at  $60 \pm 5^{\circ}\text{C}$

**Bag Seal Date:** \_\_\_\_\_

If Blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020